

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED




B0520W-MS

Product specification

Features

- Low Forward Voltage Drop
- Guard Ring Construction for Transient Protection
- High Conductance
- Also Available in Lead Free Version

Reference News

PACKAGE OUTLINE	PIN Configuration	MARKING
 SOD-123		

Maximum Ratings @Ta=25°C

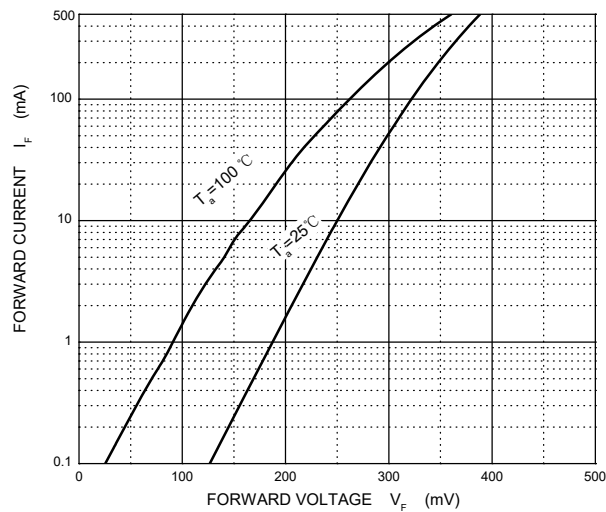
Parameter	Symbo	Value	Unit
Peak repetitive peak reverse voltage	V_{RRM}	20	V
Working peak reverse voltage	V_{RWM}		
DC blocking voltage	V_R		
RMS reverse voltage reverse voltage (DC)	$V_{R(RMS)}$	14	V
Average rectified output current	I_o	0.5	A
Non-repetitive Peak Forward Surge Current @t=8.3ms	I_{FSM}	5.5	A
Power dissipation	P_D	500	mW
Thermal resistance junction to ambient	$R_{\theta JA}$	200	°C/W
Operating Junction Temperature Range	T_j	-40 ~ +125	°C
Storage Temperature Range	T_{STG}	-55 ~ +150	°C
Voltage rate of change	dv/dt	1000	V/μs

Electrical Characteristics @Ta=25°C

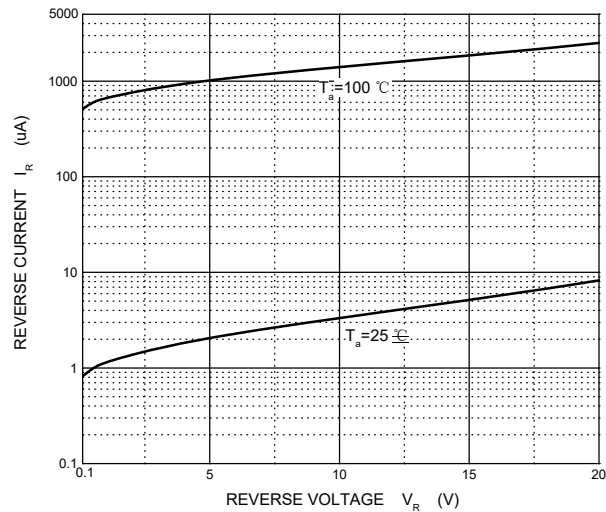
	Symbol	Test conditions	Min	Typ	Max	Unit
Reverse breakdown voltage	$V_{(BR)}$	$I_R=250\mu A$	20			V
Reverse current	I_R	$V_R=10V$			75	μA
		$V_R=20V$			250	
Forward voltage	V_F	$I_F=0.1A$			0.33	V
		$I_F=0.5A$			0.45	
Capacitance between terminals	C_T	$V_R=1, f=1MHz$		170		pF

Typical Characteristics

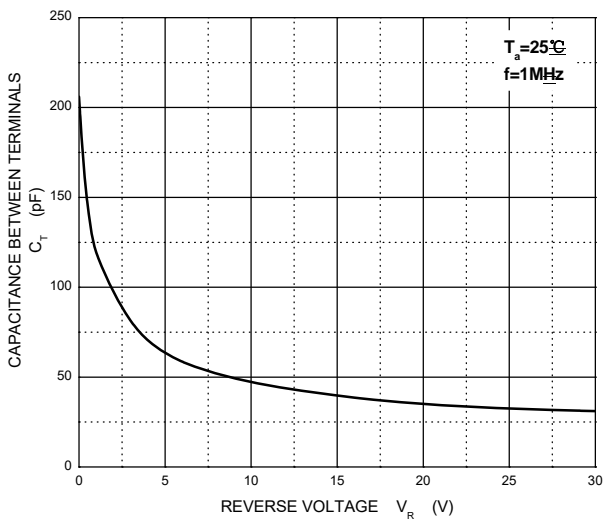
Forward Characteristics



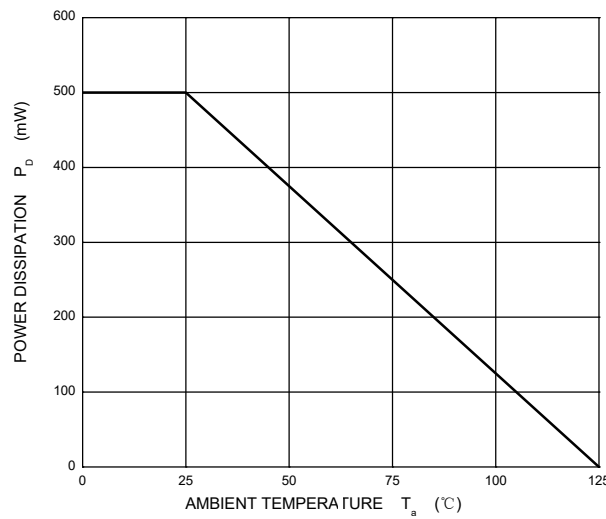
Reverse Characteristics



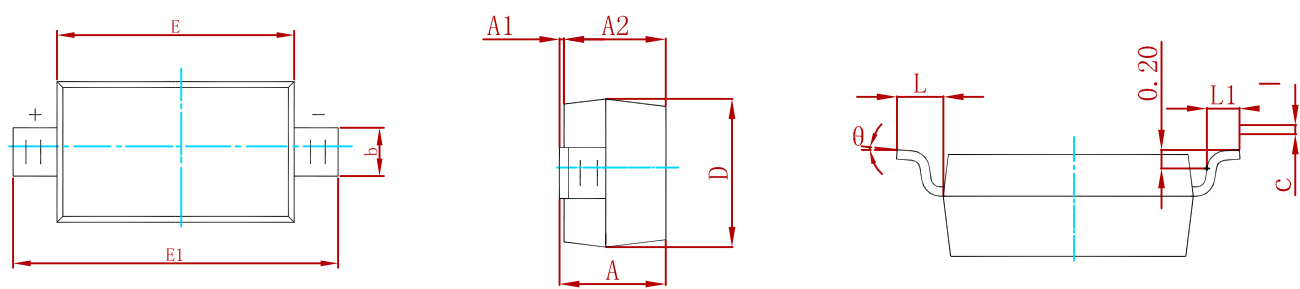
Capacitance Characteristics



Power Derating Curve

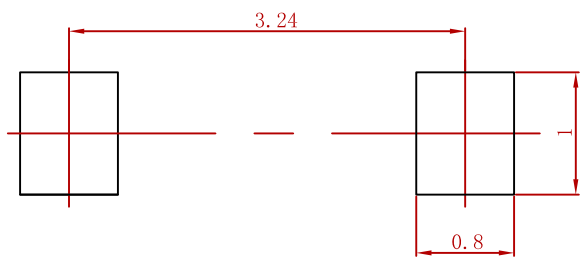


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.450	0.650	0.018	0.026
c	0.080	0.150	0.003	0.006
D	1.500	1.700	0.059	0.067
E	2.600	2.800	0.102	0.110
E1	3.550	3.850	0.140	0.152
L	0.500 REF		0.020 REF	
L1	0.250	0.450	0.010	0.018
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

REELSPECIFICATION

P/N	PKG	QTY
B0520W-MS	SOD-123	3000

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